**True BGA Socket™ Features**

- No soldering of BGA device required.
- AIC exclusive eutectic solder ball terminals offer superior processing.
- Uses same footprint as BGA device.
- Designed for production, development, programming and test applications.
- Compact design maximizes PCB real estate:
  - TSG = Device Pkg. Size + 0.216/(5.5mm)
  - TSH = Device Pkg. Size + 0.374/(9.5mm)
- Available with integral, finned heat sink or coin screw clamp assembly.
- Currently available in 1.0 and 1.27mm pitch.
- New Short Slide Clamp reduces required installation space on PCB.

**Specifications**

- **Terminals:** Brass; Copper Alloy (C36000)
- **Terminal Support:** Polyimide Film
- **Contacts:** Beryllium Copper (C17200)
- **Plating:** G – Gold over Nickel
- **Spring Material:** Beryllium Copper
- **Clamp Assembly:** Aluminum (Heat Sink/Coin Screw, Clamp, Support Plate)
- **Insulator Material:** Molded PPS (High Temp. Glass Filled Thermoplastic), U.L. Rated 94V-O, -60°C to 260°C (-76°F to 500°F)
- **Solder Ball:** Eutectic, 63Sn/37Pb, 183°C (361°F)

**How It Works**

**Step 1**
- Solder True BGA Socket™ to PCB

**Step 2**
- Align and place BGA device on top of True BGA Socket mating contacts. Place Chip Support Plate over BGA device.

**Step 3**
- Slide Clamp over assembly. Allow space on PCB for sliding clamp [approximately 33% of device package size on one side only with new Short Slide Clamp]. Refer to Clamp Sliding Directions for pin 1 location (see page 4).

**Step 4**
- Tighten Coin Screw or Finned Heat Sink to engage compression stroke.

**1.27mm Pitch Terminal Options**

- **Standard Terminals for Production Applications**
  - **Type -690**
  - **Type -708**

- **Terminals for LGA or De-balled BGA Device Applications**
  - **Type -712**
  - **Type -713**

**1.0mm Pitch Terminal**

- **Type -752**

**How To Order**

- **Footprint Dash #** If Applicable*
- **True BGA Socket™ Pitch**
  - G = .050/(1.27mm) pitch
  - H = .039/(1.0mm) pitch
- **Number of Positions**
  - See BGA Footprint Booklet or web site
- **Terminal Type** See options above
- **Clamp Options**
  - YH - Heat Sink (3 Fins Std.)
  - YC - Coin Screw
- **Contact Plating**
  - G - Gold
- **Terminal Plating**
  - G - Gold

Mechanical specifications for BGA device package required for quoting/ordering.